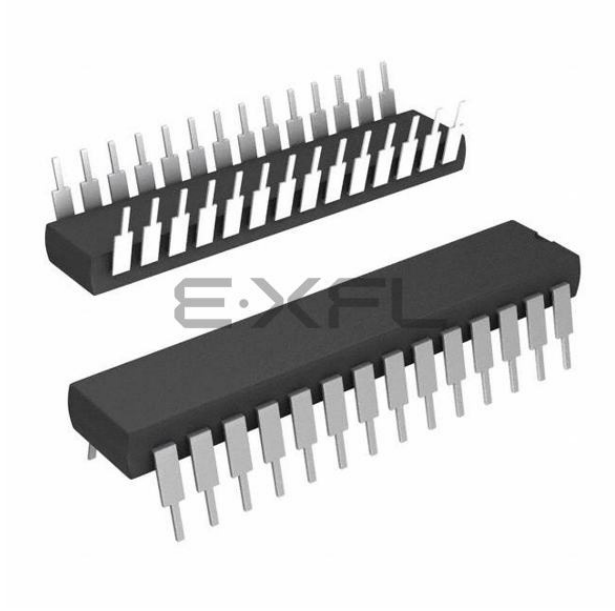

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c72-20-sp

1.0 DEVICE OVERVIEW

This document contains device-specific information for the operation of the PIC16C72 device. Additional information may be found in the PIC® Mid-Range MCU Reference Manual (DS33023) which may be downloaded from the Microchip website. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC16C72 belongs to the Mid-Range family of the PIC devices. A block diagram of the device is shown in Figure 1-1.

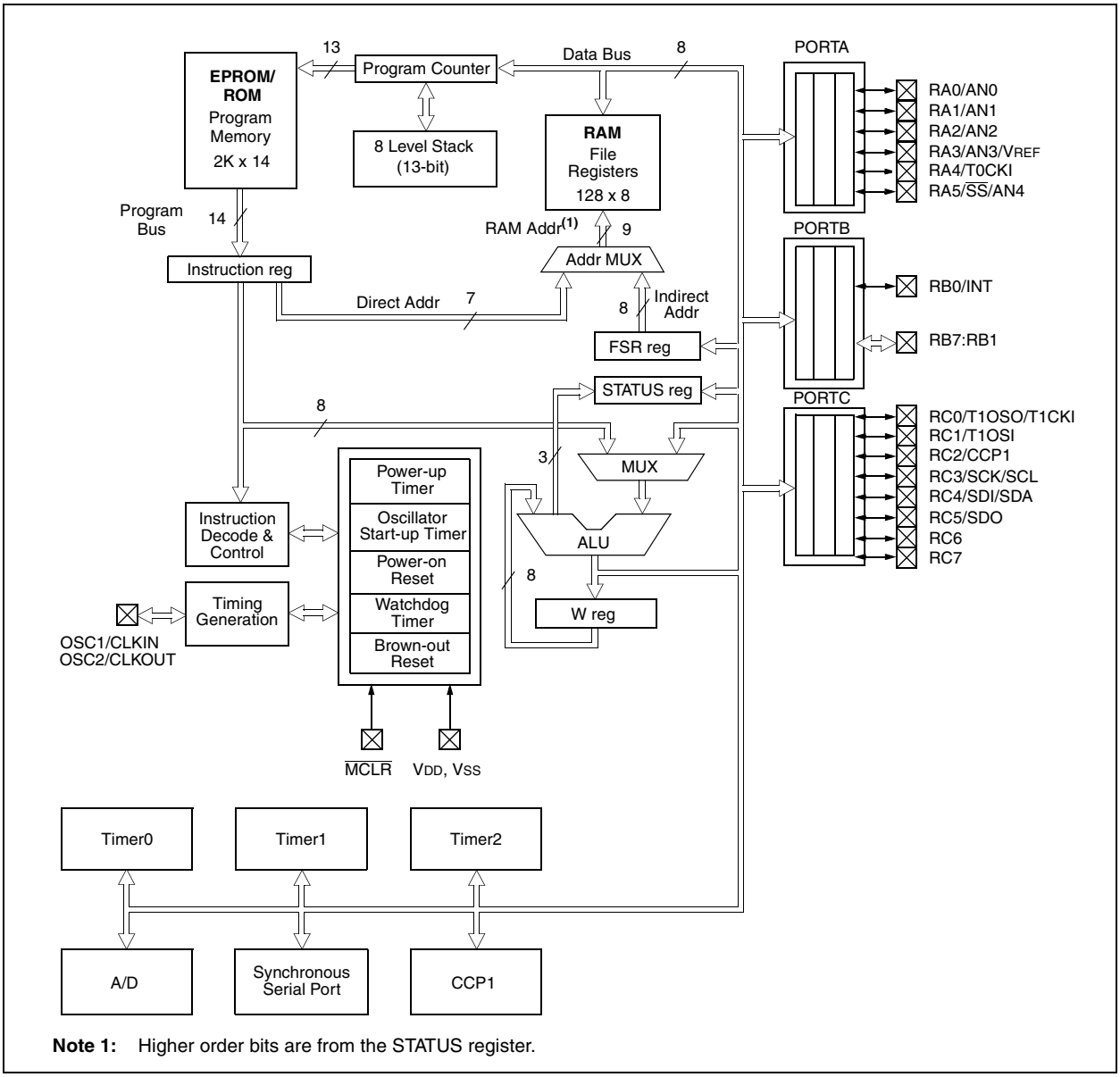
The program memory contains 2K words which translate to 2048 instructions, since each 14-bit program memory word is the same width as each device instruction. The data memory (RAM) contains 128 bytes.

There are also 22 I/O pins that are user-configurable on a pin-to-pin basis. Some pins are multiplexed with other device functions. These functions include:

- External interrupt
- Change on PORTB interrupt
- Timer0 clock input
- Timer1 clock/oscillator
- Capture/Compare/PWM
- A/D converter
- SPI/I^2C

Table 1-1 details the pinout of the device with descriptions and details for each pin.

FIGURE 1-1: PIC16C72/CR72 BLOCK DIAGRAM



Note 1: Higher order bits are from the STATUS register.

2.2.2.5 PIR1 REGISTER

This register contains the individual flag bits for the Peripheral interrupts.

Note:	Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-7: PIR1 REGISTER (ADDRESS 0Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ADIF	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6: **ADIF**: A/D Converter Interrupt Flag bit
1 = An A/D conversion completed (must be cleared in software)
0 = The A/D conversion is not complete

bit 5-4: **Unimplemented**: Read as '0'

bit 3: **SSPIF**: Synchronous Serial Port Interrupt Flag bit
1 = The transmission/reception is complete (must be cleared in software)
0 = Waiting to transmit/receive

bit 2: **CCP1IF**: CCP1 Interrupt Flag bit
Capture Mode
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare Mode
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM Mode
Unused in this mode

bit 1: **TMR2IF**: TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0: **TMR1IF**: TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflowed (must be cleared in software)
0 = TMR1 register did not overflow

2.2.2.6 PCON REGISTER

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external $\overline{MCLR}$ Reset or WDT Reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note:	$\overline{BOR}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{BOR}$ is clear, indicating a brown-out has occurred. The $\overline{BOR}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 2-8: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

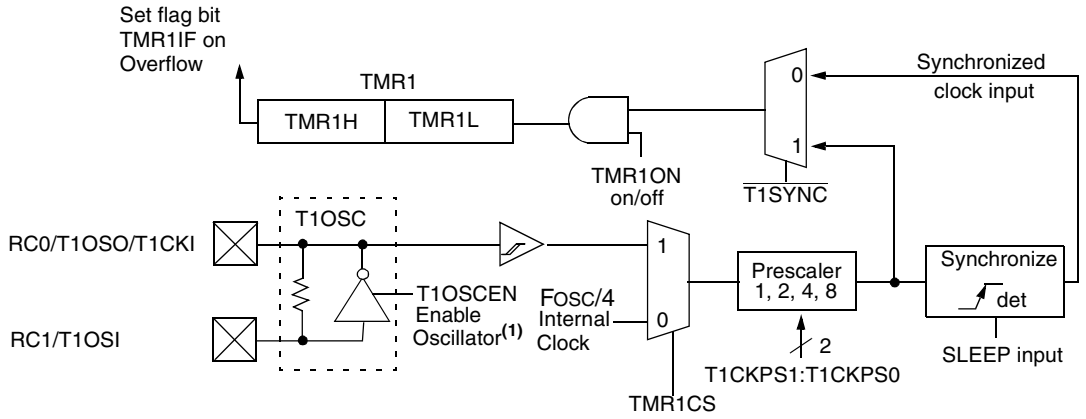
bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{BOR}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

NOTES:

FIGURE 5-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.

5.2 Timer1 Oscillator

A crystal oscillator circuit is built in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low power oscillator rated up to 200 kHz. It will continue to run during SLEEP. It is primarily intended for a 32 kHz crystal. Table 5-1 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must provide a software time delay to ensure proper oscillator start-up.

TABLE 5-1 CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

Osc Type	Freq	C1	C2
LP	32 kHz	33 pF	33 pF
	100 kHz	15 pF	15 pF
	200 kHz	15 pF	15 pF
These values are for design guidance only.			
Crystals Tested:			
32.768 kHz	Epson C-001R32.768K-A		± 20 PPM
100 kHz	Epson C-2 100.00 KC-P		± 20 PPM
200 kHz	STD XTL 200.000 kHz		± 20 PPM

Note 1: Higher capacitance increases the stability of oscillator but also increases the start-up time.
2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

5.3 Timer1 Interrupt

The TMR1 Register pair (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 Interrupt, if enabled, is generated on overflow which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing TMR1 interrupt enable bit TMR1IE (PIE1<0>).

5.4 Resetting Timer1 using a CCP Trigger Output

If the CCP module is configured in compare mode to generate a “special event trigger" (CCP1M3:CCP1M0 = 1011), this signal will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Note: The special event triggers from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

Timer1 must be configured for either timer or synchronized counter mode to take advantage of this feature. If Timer1 is running in asynchronous counter mode, this reset operation may not work.

In the event that a write to Timer1 coincides with a special event trigger from CCP1, the write will take precedence.

In this mode of operation, the CCPR1H:CCPR1L registers pair effectively becomes the period register for Timer1.

TABLE 5-2 REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the Timer1 module.
Note 1: These bits are unimplemented, read as '0'.

7.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RC2/CCP1. An event is defined as:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

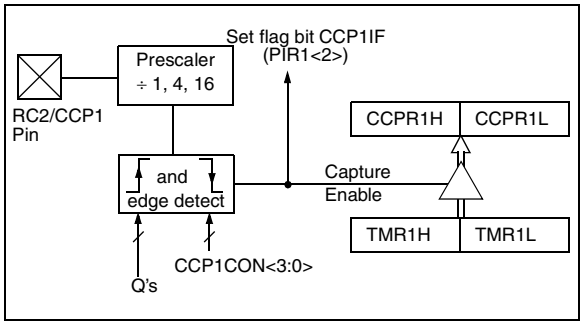
An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

7.1.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note:	If the RC2/CCP1 is configured as an output, a write to the port can cause a capture condition.

FIGURE 7-2: CAPTURE MODE OPERATION BLOCK DIAGRAM



7.1.2 TIMER1 MODE SELECTION

Timer1 must be running in timer mode or synchronized counter mode for the CCP module to use the capture feature. In asynchronous counter mode, the capture operation may not work.

7.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit CCP1IF following any such change in operating mode.

7.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in capture mode, the prescaler counter is cleared. This means that any reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 7-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

EXAMPLE 7-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF    CCP1CON      ;Turn CCP module off
MOVLW   NEW_CAPT_PS  ;Load the W reg with
                     ; the new prescaler
                     ; mode value and CCP ON
MOVWF   CCP1CON      ;Load CCP1CON with this
                     ; value
```

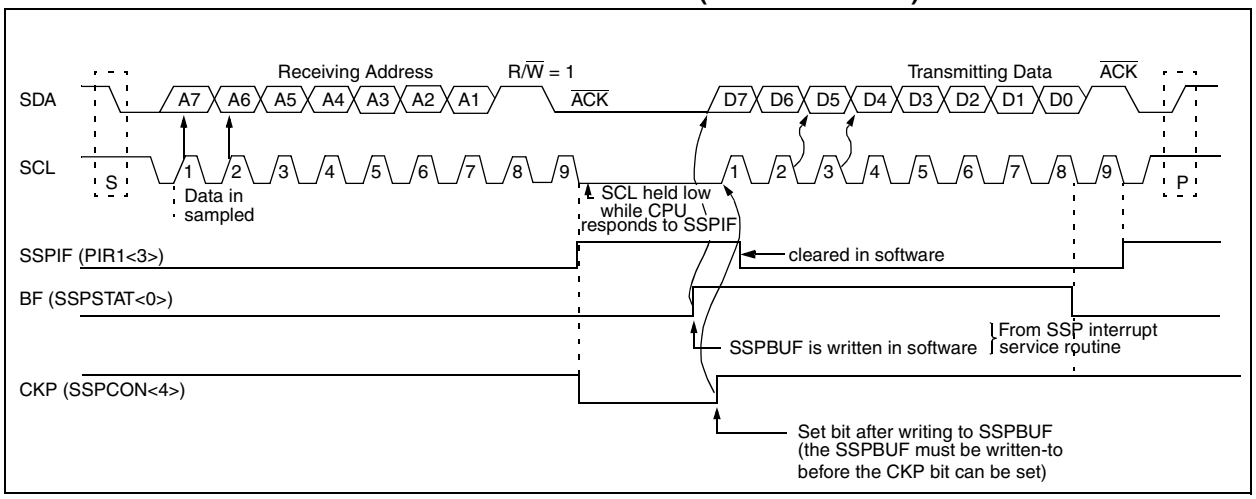

8.4.1.3 TRANSMISSION

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit, and pin RC3/SCK/SCL is held low. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP (SSPCON<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 8-9).

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF must be cleared in software, and the SSPSTAT register is used to determine the status of the byte. Flag bit SSPIF is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{ACK}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not $\overline{ACK}$), then the data transfer is complete. When the $\overline{ACK}$ is latched by the slave, the slave logic is reset (resets SSPSTAT register) and the slave then monitors for another occurrence of the START bit. If the SDA line was low ($\overline{ACK}$), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP.

FIGURE 8-9: I²C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)

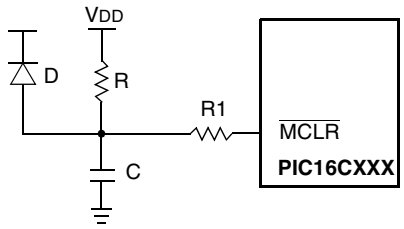


10.4 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details. For a slow rise time, see Figure 10-6.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

FIGURE 10-6: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

10.5 Power-up Timer (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

10.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

10.7 Brown-Out Reset (BOR)

A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (3.8V - 4.2V range) for greater than parameter #35, the brown-out situation will reset the chip. A reset may not occur if VDD falls below 4.0V for less than parameter #35. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms. If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms time delay. The Power-up Timer should always be enabled when Brown-out Reset is enabled.

13.1 DC Characteristics: PIC16C72/CR72-04 (Commercial, Industrial, Extended) PIC16C72/CR72-10 (Commercial, Industrial, Extended) PIC16C72/CR72-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial

Param No.	Characteristic	Sym	PIC16C72			PIC16CR72			Units	Conditions
			Min	Typ†	Max	Min	Typ†	Max		
D001	Supply Voltage	VDD	4.0	-	**6.0**	4.0	-	**5.5**	V	XT, RC and LP osc
D001A			4.5	-	5.5	4.5	-	5.5	V	HS osc
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset Signal	VPOR	-	VSS	-	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset Signal	SVDD	0.05	-	-	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	3.7	4.0	4.4	V	Extended Only
D010	Supply Current (Note 2,5)	IDD	-	2.7	5.0	-	2.7	5.0	mA	XT, RC osc FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	-	10	20	mA	HS osc FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	µA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3,5)	IPD	-	10.5	42	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	16	-	1.5	16	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	19	-	1.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	2.5	19	-	2.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

Note 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

Note 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

Note 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

Note 5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

Note 6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 13.1 and Section 13.2.

Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD - 0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D090A			VDD - 0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D092A			VDD - 0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°C to +125°C
D150*	**Open-Drain High Voltage**	Vod	-	-	14	V	RA4 pin, PIC16**C**72/**LC**72
			-	-	TBD	V	RA4 pin, PIC16**CR**72/**LCR**72
	Capacitive Loading Specs on Output Pins						
D100	OSC2 pin	COSC2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	CIO	-	-	50	pF	
D102	SCL, SDA in I^2C mode	Cb	-	-	400	pF	

* These parameters are characterized but not tested.

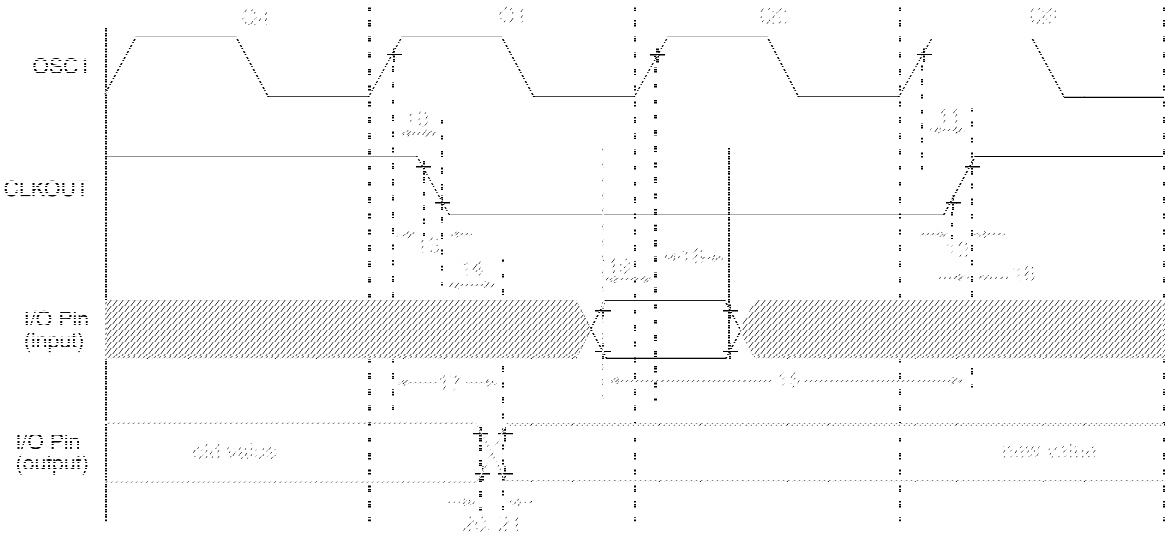
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

Note 2: The leakage current on the $\overline{MCLR}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

Note 3: Negative current is defined as current sourced by the pin.

FIGURE 13-3: CLKOUT AND I/O TIMING



Note: Refer to Figure 13-1 for load conditions.

TABLE 13-4 CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid		—	—	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑		TOSC + 200	—	—	ns	Note 1
16*	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		—	50	150	ns	
18*	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	PIC16**C**72/**CR**72	100	—	—	ns	
			PIC16**LC**72/**LCR**72	200	—	—	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)		0	—	—	ns	
20*	TioR	Port output rise time	PIC16**C**72/**CR**72	—	10	40	ns	
			PIC16**LC**72/**LCR**72	—	—	80	ns	
21*	TioF	Port output fall time	PIC16**C**72/**CR**72	—	10	40	ns	
			PIC16**LC**72/**LCR**72	—	—	80	ns	
22††*	Tinp	INT pin high or low time		TCY	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low time		TCY	—	—	ns	

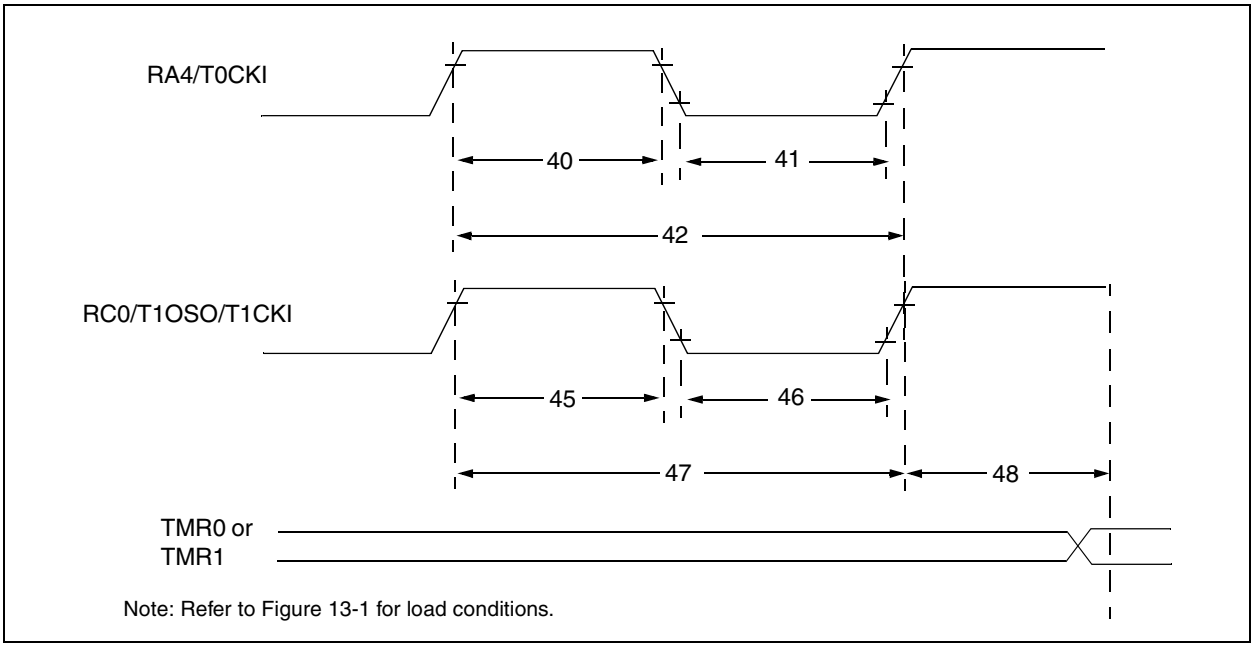
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

FIGURE 13-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Note: Refer to Figure 13-1 for load conditions.

TABLE 13-6 TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
				With Prescaler	Greater of: 20 or TCY + 40 / N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	PIC16**C**7X/**CR**72	15	—	—	ns	
				PIC16**LC**7X/**LCR**72	25	—	—	ns	
			Asynchronous	PIC16**C**7X/**CR**72	30	—	—	ns	
				PIC16**LC**7X/**LCR**72	50	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	PIC16**C**7X/**CR**72	15	—	—	ns	
				PIC16**LC**7X/**LCR**72	25	—	—	ns	
			Asynchronous	PIC16**C**7X/**CR**72	30	—	—	ns	
				PIC16**LC**7X/**LCR**72	50	—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16**C**7X/**CR**72	Greater of: 30 OR TCY + 40 / N	—	—	ns	N = prescale value (1, 2, 4, 8)
				PIC16**LC**7X/**LCR**72	Greater of: 50 OR TCY + 40 / N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16**C**7X/**CR**72	60	—	—	ns	
				PIC16**LC**7X/**LCR**72	100	—	—	ns	
	Ft1	Timer1 oscillator input frequency range (oscillator enabled by setting bit T1OSCEN)			DC	—	200	kHz	
48	TCKEZtmr1	Delay from external clock edge to timer increment			2Tosc	—	7Tosc	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-10: SPI SLAVE MODE TIMING (CKE = 0)

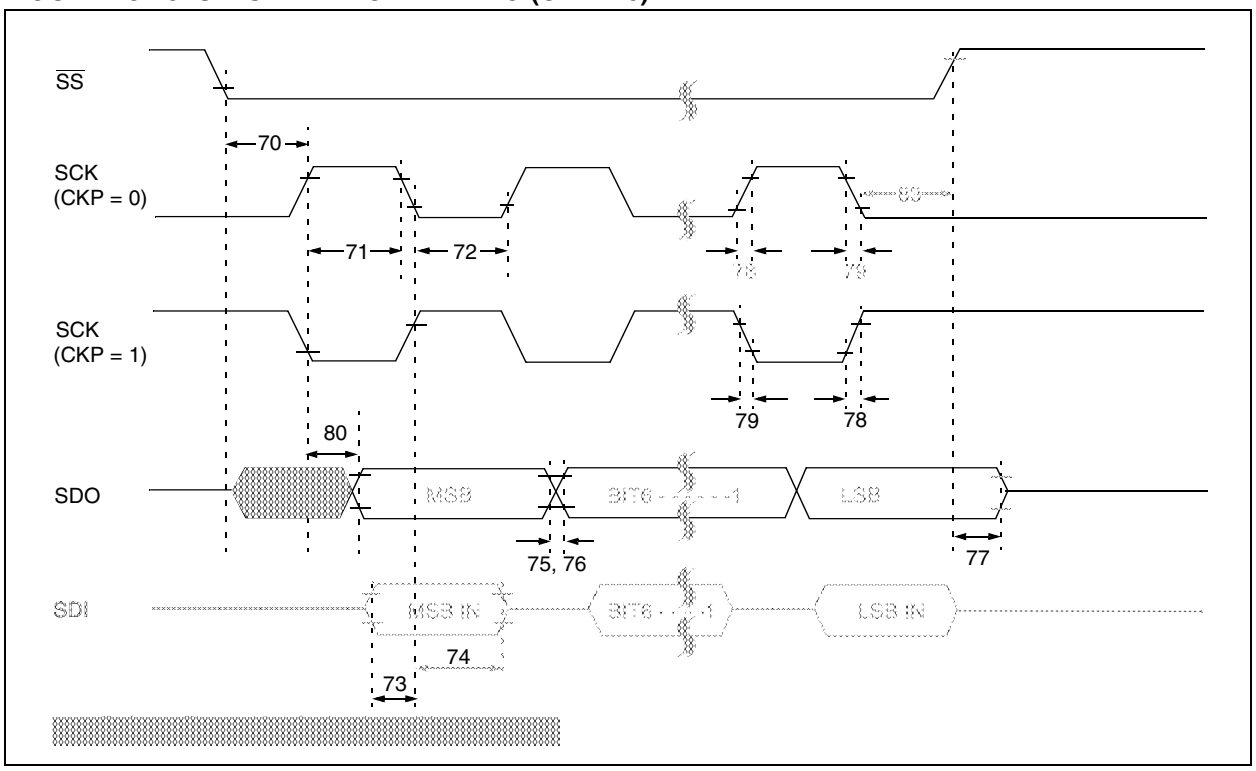


FIGURE 13-11: SPI SLAVE MODE TIMING (CKE = 1)

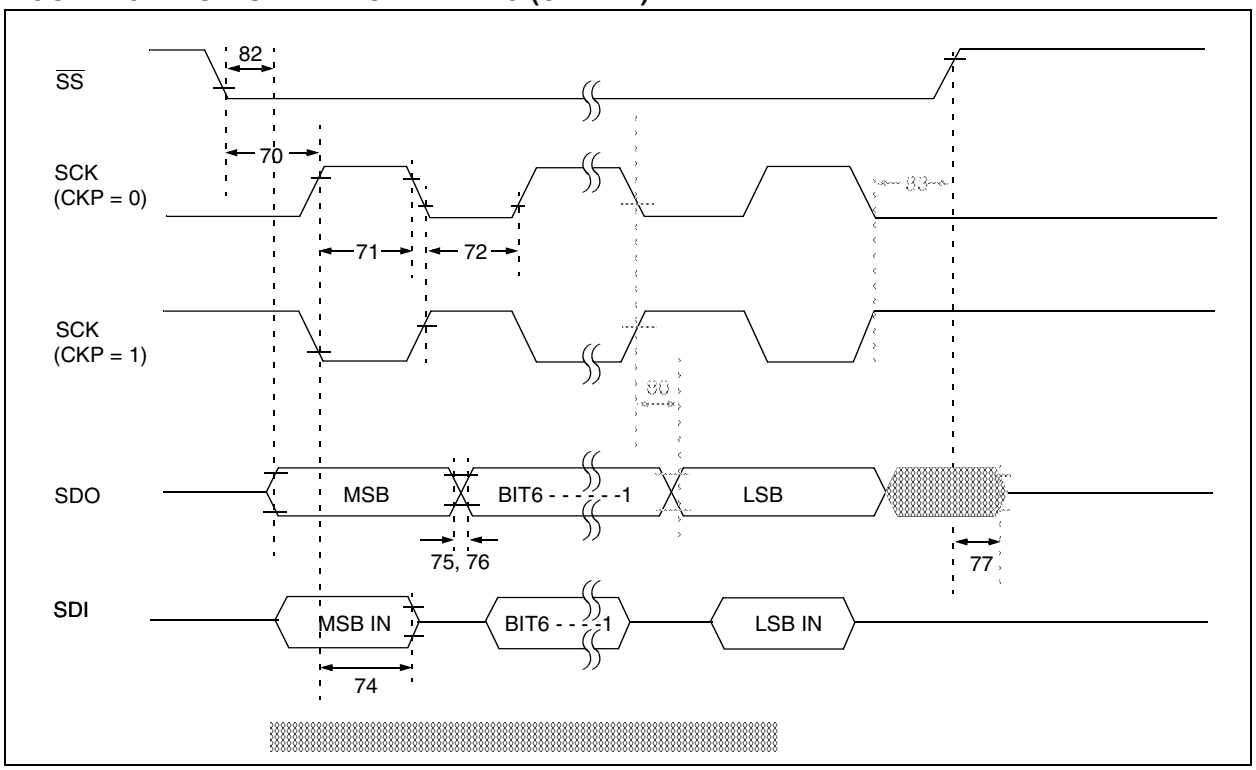
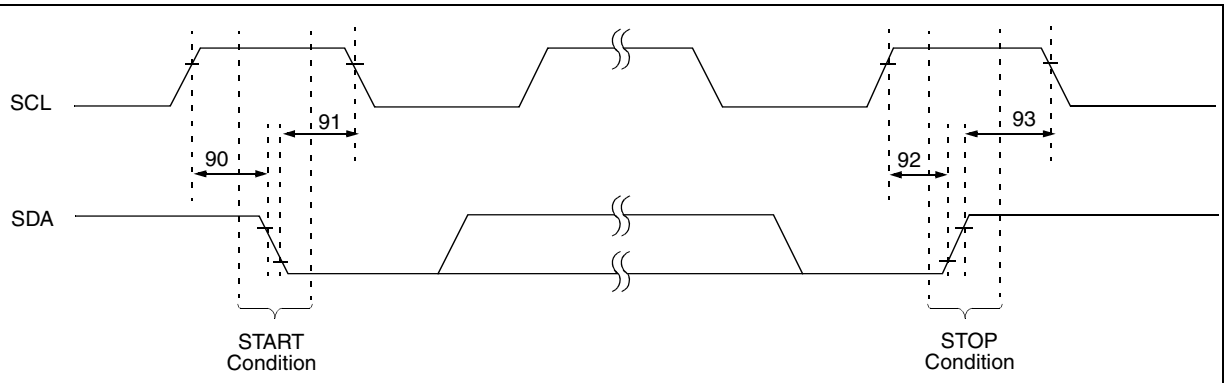


FIGURE 13-12: I^2C BUS START/STOP BITS TIMING



Note: Refer to Figure 13-1 for load conditions

TABLE 13-10 I^2C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90	TSU:STA	START condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
			400 kHz mode	600	—	—		
91	THD:STA	START condition Hold time	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
			400 kHz mode	600	—	—		
92	TSU:STO	STOP condition Setup time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
93	THD:STO	STOP condition Hold time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

TABLE 13-12 A/D CONVERTER CHARACTERISTICS:
PIC16C72/CR72-04 (Commercial, Industrial, Extended)
PIC16C72/CR72-10 (Commercial, Industrial, Extended)
PIC16C72/CR72-20 (Commercial, Industrial, Extended)
PIC16LC72/LCR72-04 (Commercial, Industrial)

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		—	—	8 bits	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A02	EABS	Total Absolute error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A05	EFS	Full scale error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity		—	guaranteed	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage		2.5V	—	VDD + 0.3	V	
A25	VAIN	Analog input voltage		VSS - 0.3	—	VREF + 0.3	V	
A30	ZAIN	Recommended impedance of analog voltage source		—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	PIC16**C**72/**CR**72	—	180	—	μA	Average current consumption when A/D is on. (Note 1)
			PIC16**LC**72/**LCR**72	—	90	—	μA	
A50	IREF	VREF input current (Note 2)		10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 9.1.
				—	—	10	μA	During A/D Conversion cycle

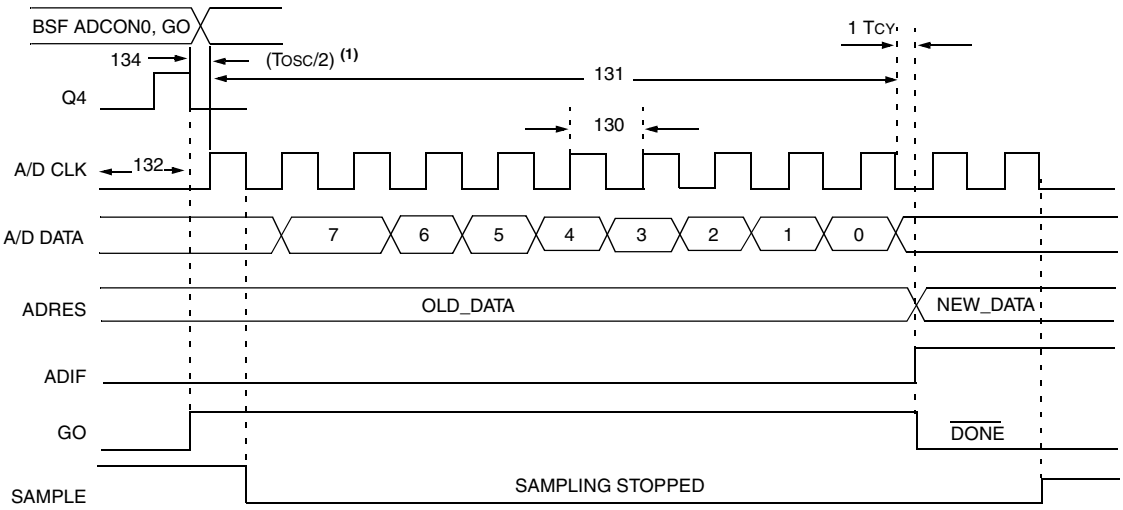
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

Note 2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

FIGURE 13-14: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 13-13 A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	PIC16**C**72/**LCR**72	1.6	—	—	µs	TOSC based, VREF ≥ 2.5V
			PIC16**LC**72/**LCR**72	2.0	—	—	µs	TOSC based, VREF full range
			PIC16**C**72/**LCR**72	2.0	4.0	6.0	µs	A/D RC Mode
			PIC16**LC**72/**LCR**72	2.5	6.0	9.0	µs	A/D RC Mode
131	TCNV	Conversion time (not including S/H time) (Note 1)		—	9.5	—	TAD	
132	TACQ	Acquisition time		Note 2	20	—	µs	
				5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 20.0 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
134	Tgo	Q4 to A/D clock start		—	TOSC/2 §	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	Tswc	Switching from convert → sample time		1.5 §	—	—	TAD	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Note 1: ADRES register may be read on the following TCY cycle.

Note 2: See Section 9.1 for min conditions.

FIGURE 14-29: TYPICAL IDD vs. FREQUENCY (HS MODE, 25°C)

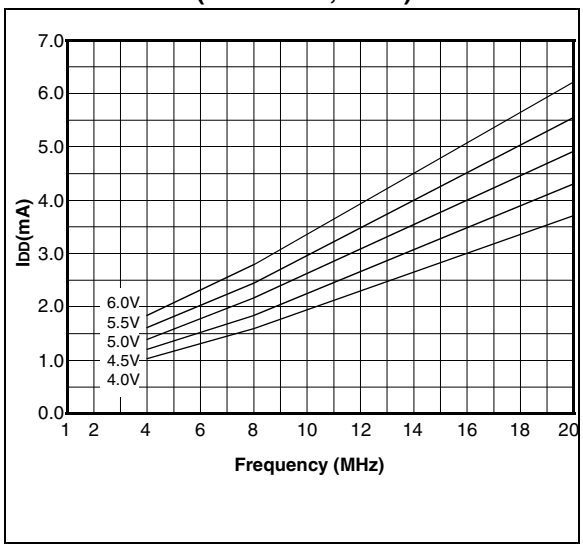


FIGURE 14-30: MAXIMUM IDD vs. FREQUENCY (HS MODE, -40°C TO 85°C)

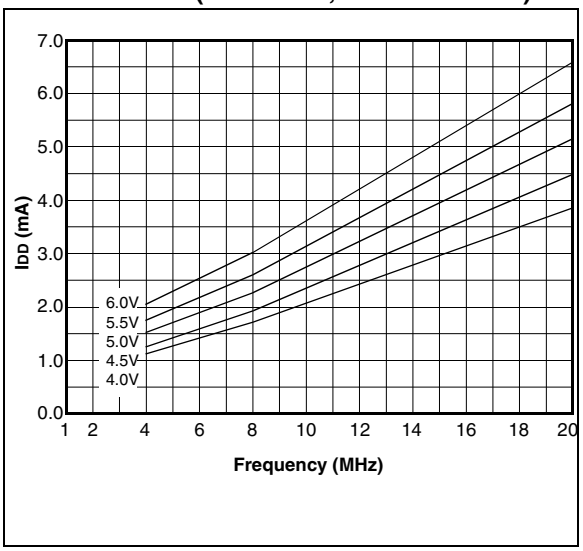


TABLE 14-3 TYPICAL EPROM ERASE TIME RECOMMENDATIONS

Process Technology	Wavelength (Angstroms)	Intensity (μW/ cm2)	Distance from UV lamp (inches)	Typical Time (1) (minutes)
57K	2537	12,000	1	15 - 20
77K	2537	12,000	1	20
90K	2537	12,000	1	40
120K	2537	12,000	1	60

Note 1: If these criteria are not met, the erase times will be different.

Note: Fluorescent lights and sunlight both emit ultraviolet light at the erasure wavelength. Leaving a UV erasable device's window uncovered could cause, over time, the devices memory cells to become erased. The erasure time for a fluorescent light is about three years. While sunlight requires only about one week. To prevent the memory cells from losing data an opaque label should be placed over the erasure window.

Data based on matrix samples. See first page of this section for details.

